

CLAIMS

1. A wafer support tool for heat treatment comprising:
a plurality of wafer support members for supporting a wafer to be
5 heat treated; and
a support member holder for holding the wafer support members,
wherein the wafer support members each has a contact portion with
the wafer, at least one of the contact portions being movable relative to the
support member holder.
- 10 2. The wafer support tool for heat treatment according to claim 1,
wherein a configuration of the contact portion is a curved surface convex
against the wafer to be heat treated.
3. The wafer support tool for heat treatment according to claim 1 or 2,
wherein a configuration of the contact portion is spherical or ellipsoidal.
- 15 4. The wafer support tool for heat treatment according to any of claims
1 to 3, wherein the wafer support member is a pin, the support member
holder is a pin holder for holding the pin and the pin is fitted in a pinhole
formed in the pin holder.
5. The wafer support tool for heat treatment according to claim 4,
20 wherein the pin is removable from the pin holder.
6. The wafer support tool for heat treatment according to claim 4 or 5,
wherein the pin is formed by working a cylindrical body.
7. The wafer support tool for heat treatment according to any of claims
4 to 6, wherein raw material of the pin and the pin holder is SiC, silicon or
25 quartz.
8. The wafer support tool for heat treatment according to any of claims

4 to 7, wherein a plurality of pinholes is provided.

9. The wafer support tool for heat treatment according to any of claims 4 to 8, wherein the pinhole is slit-shaped.

10. The wafer support tool for heat treatment according to claim 9,
5 wherein the slit-shaped pinholes are provided radially from the center of the pin holder.

11. The wafer support tool for heat treatment according to any of claims 4 to 10, wherein the pin holder is disc-shaped or ring-shaped.

12. The wafer support tool for heat treatment according to claim 11,
10 wherein the pin holder is disc-shaped and a circular pinhole is formed in the center position thereof.

13. The wafer support tool for heat treatment according to claim 1 or 2, wherein the wafer support member comprises a rotatable body as the contact portion with the wafer to be heat treated, and the rotatable body is
15 accommodated in a rotatable body accommodating hole formed in the wafer support member or the support member holder and rotatable by friction force with the wafer to be heat treated.

14. The wafer support tool for heat treatment according to claim 13, wherein the rotatable body is in the form of a sphere, an ellipsoid, a hollow
20 cylinder or a solid cylinder.

15. The wafer support tool for heat treatment according to claim 13 or 14, wherein the rotatable body accommodating hole is in the form of a slit groove.

16. The wafer support tool for heat treatment according to claim 15,
25 wherein the rotatable body accommodating holes each in the form of a slit groove are formed radially from the center of the support member holder.

17. The wafer support tool for heat treatment according to any of claims 13 to 16, wherein the support member holder is disc-shaped or ring-shaped.

18. The wafer support tool for heat treatment according to any of claims 13 to 17, wherein material of the rotatable body is SiC, silicon or quartz.

5 19. The wafer support tool for heat treatment according to any of claims 1 to 18, further comprising: support poles for holding the plural support member holders; and bases for holding the support poles.

20. The wafer support tool for heat treatment according to claim 19, wherein the support member holders are removable from the support poles.

10 21 The wafer support tool for heat treatment according to claim 19 or 20, wherein material of the support poles and the bases is SiC, silicon or quartz.

22. A heat treatment apparatus having the wafer support tool for heat treatment according to any of claims 1 to 21.